



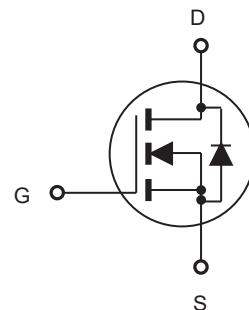
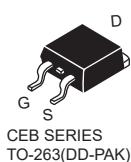
# CEP02N65B/CEB02N65B CEF02N65B

## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

Type	$V_{DSS}@T_J \text{ max}$	$R_{DS(\text{ON})}$	$I_D$	$@V_{GS}$
CEP02N65B	700V	5Ω	2A	10V
CEB02N65B	700V	5Ω	2A	10V
CEF02N65B	700V	5Ω	2A <sup>d</sup>	10V

- Super high dense cell design for extremely low  $R_{DS(\text{ON})}$ .
- High power and current handing capability.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.



### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit		Units
		TO-220/263	TO-220F	
Drain-Source Voltage	$V_{DS}$	650		V
Gate-Source Voltage	$V_{GS}$	$\pm 30$		V
Drain Current-Continuous @ $T_C = 25^\circ\text{C}$ @ $T_C = 100^\circ\text{C}$	$I_D$	2	2 <sup>d</sup>	A
		1.3	1.3 <sup>d</sup>	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}^e$	8	8 <sup>d</sup>	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above 25°C	$P_D$	52	28	W
		0.41	0.22	W/°C
Single Pulsed Avalanche Energy <sup>g</sup>	$E_{AS}$	11.25		mJ
Single Pulsed Avalanche Current <sup>g</sup>	$I_{AS}$	1.5		A
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150		°C

### Thermal Characteristics

Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	$R_{JC}$	2.4	4.5	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{JA}$	62.5	65	°C/W



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## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics</b> <sup>b</sup>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 1\text{A}$		4.2	5	$\Omega$
<b>Dynamic Characteristics</b> <sup>c</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		365		pF
Output Capacitance	$C_{\text{oss}}$			65		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			20		pF
<b>Switching Characteristics</b> <sup>c</sup>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 300\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 18\Omega$		22		ns
Turn-On Rise Time	$t_r$			12		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			34		ns
Turn-Off Fall Time	$t_f$			11		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 300\text{V}, I_D = 0.5\text{A}, V_{\text{GS}} = 10\text{V}$		7.2		nC
Gate-Source Charge	$Q_{\text{gs}}$			1.3		nC
Gate-Drain Charge	$Q_{\text{gd}}$			2.8		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$ <sup>f</sup>			2		A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 1\text{A}$		1.5		V
<b>Notes :</b>						
a.Repetitive Rating : Pulse width limited by maximum junction temperature .						
b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$ .						
c.Guaranteed by design, not subject to production testing.						
d.Limited only by maximum temperature allowed .						
e.Pulse width limited by safe operating area .						
f.Full package $I_{\text{S}(\text{max})} = 1.5\text{A}$ .						
g. $L = 10\text{mH}, I_{\text{AS}} = 1.5\text{A}, V_{\text{DD}} = 50\text{V}, R_G = 25\Omega$ , Starting $T_J = 25^\circ\text{C}$ .						

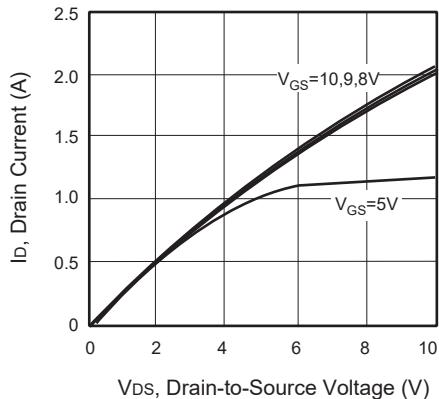


Figure 1. Output Characteristics

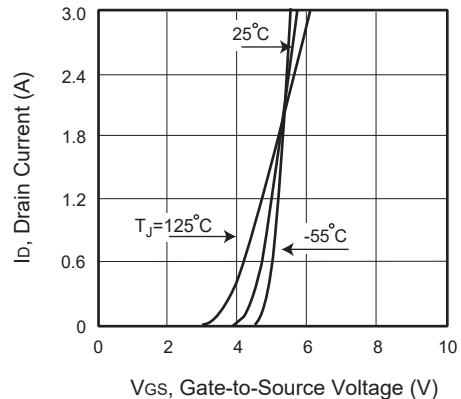


Figure 2. Transfer Characteristics

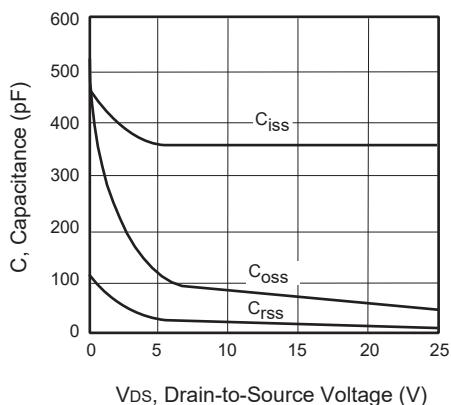


Figure 3. Capacitance

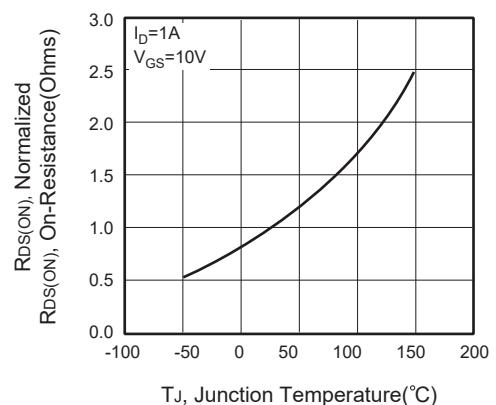


Figure 4. On-Resistance Variation with Temperature

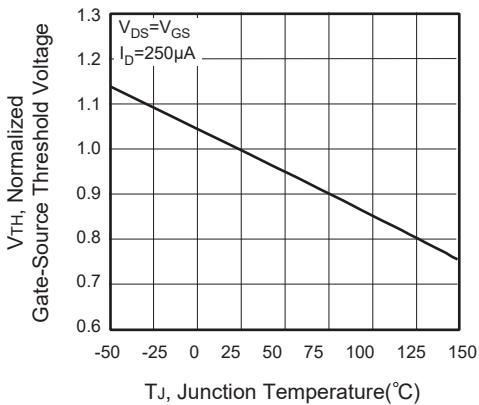


Figure 5. Gate Threshold Variation with Temperature

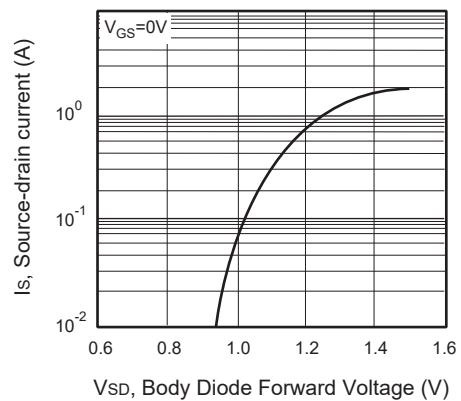


Figure 6. Body Diode Forward Voltage Variation with Source Current



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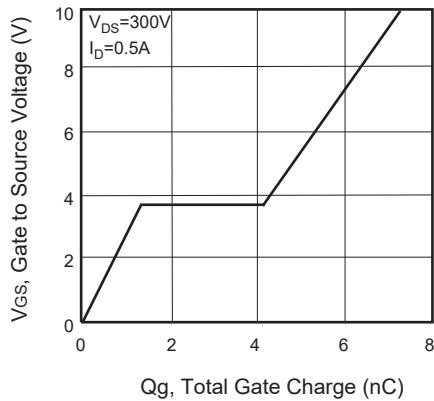


Figure 7. Gate Charge

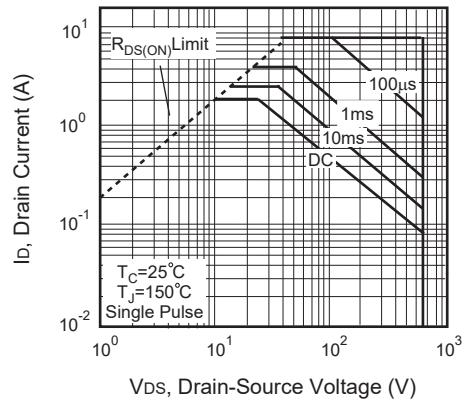


Figure 8. Maximum Safe  
Operating Area

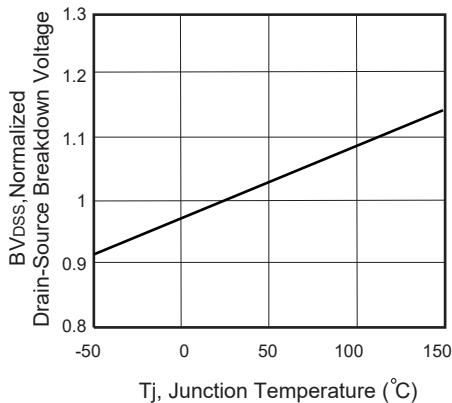


Figure 9. Breakdown Voltage Variation  
VS Temperature

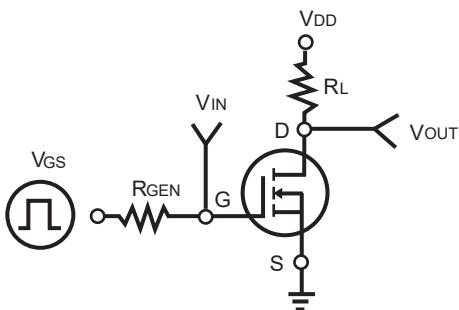


Figure 10. Switching Test Circuit

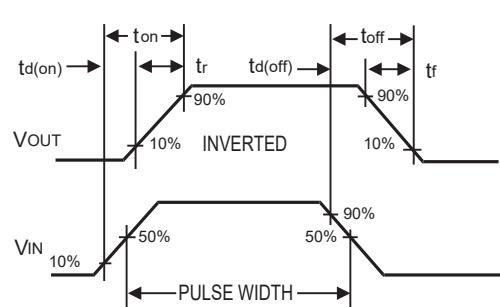


Figure 11. Switching Waveforms



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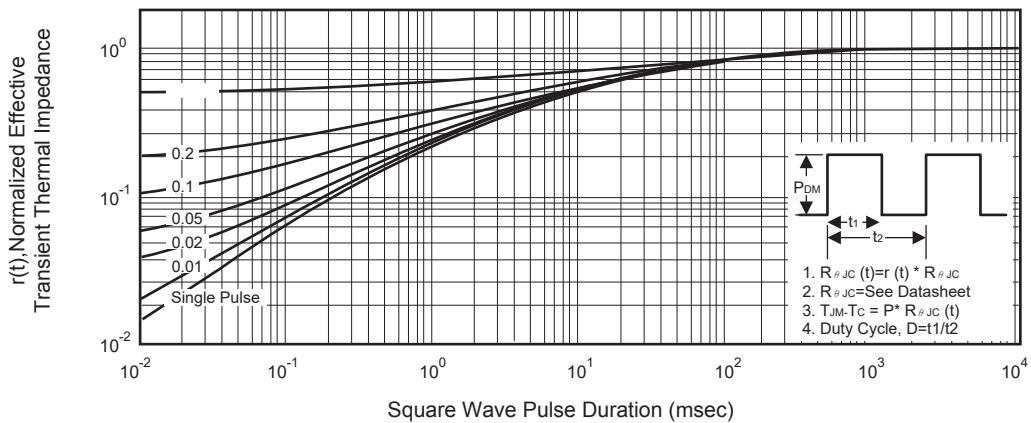


Figure 12. Normalized Thermal Transient Impedance Curve